



Material Content Data Sheet



Sales Product Name		IPC70N04S5L-4R2		Issued		1. August 2018		
MA#		MA001496394						
Package		PG-TDSON-8-33		Weight*		111.26 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	0.348	0.31	0.31	3126	3126
leadframe	inorganic material	phosphorus	7723-14-0	0.016	0.01		144	
	non noble metal	iron	7439-89-6	0.053	0.05		478	
	non noble metal	copper	7440-50-8	53.151	47.79	47.85	477741	478363
	noble metal	gold	7440-57-5	0.046	0.04	0.04	416	416
wire	organic material	carbon black	1333-86-4	0.077	0.07		692	
encapsulation	plastics	epoxy resin	-	6.078	5.46		54630	
	inorganic material	silicondioxide	60676-86-0	32.313	29.04	34.57	290437	345759
leadfinish	non noble metal	tin	7440-31-5	1.574	1.41	1.41	14146	14146
plating	noble metal	silver	7440-22-4	0.209	0.19	0.19	1881	1881
solder	non noble metal	tin	7440-31-5	0.011	0.01		97	
	noble metal	silver	7440-22-4	0.014	0.01		122	
heat sink CLIP	non noble metal	lead	7439-92-1	0.517	0.46	0.48	4643	4862
	inorganic material	phosphorus	7723-14-0	0.005	0.00		45	
	non noble metal	iron	7439-89-6	0.017	0.02		151	
	non noble metal	copper	7440-50-8	16.828	15.13	15.15	151251	151447
*deviation	< 10%		Sum in total:			100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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